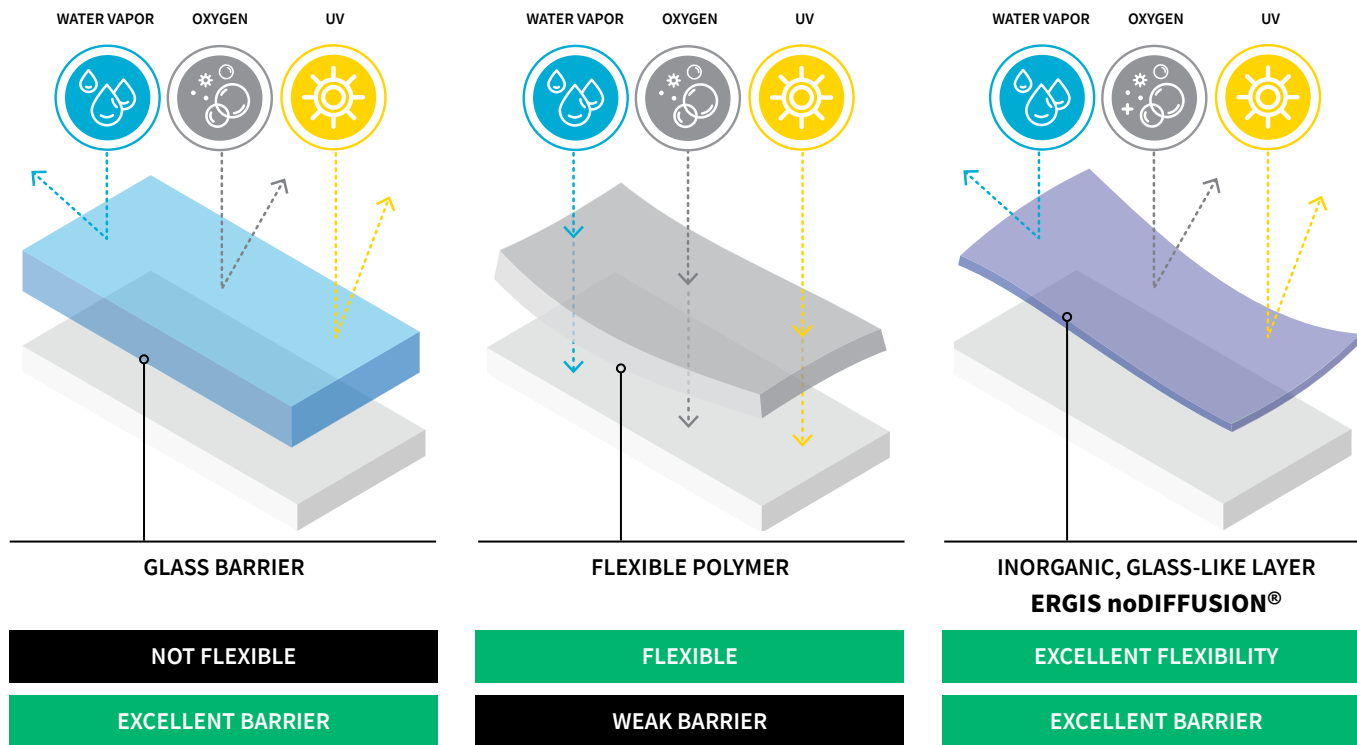


The background features a dynamic, abstract design with flowing, wavy lines in various shades of blue, from deep navy to light sky blue, set against a white base. The lines create a sense of movement and depth, particularly in the lower half of the image.

Ergis ultra barrier film
noDiffusion[®]

innovation in encapsulation

A CURRENT ELECTRONICS MARKET TREND is the fabrication of various flexible electronic devices (like flexible displays and solar cells), that require a flexible substrate material.





CAGR > 10%

**FLEXIBLE ELECTRONICS IS
ONE OF THE FASTEST GROWING
MARKETS**

SUBSTRATE AND ENCAPSULATION

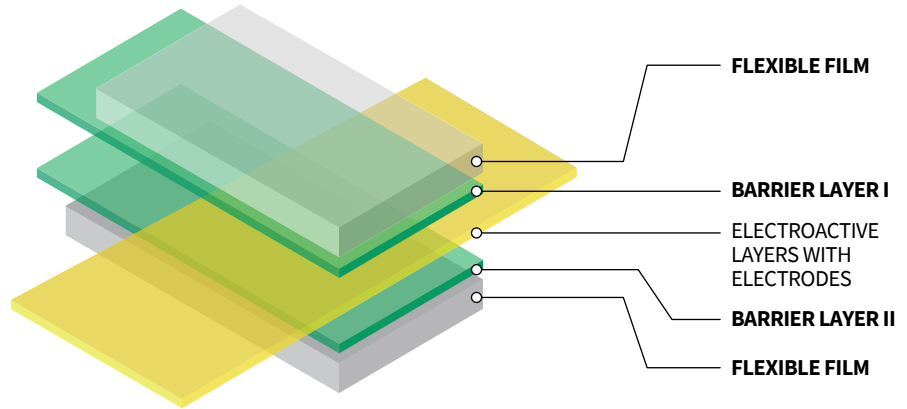
are among the most significant deterrents due to their relatively high price, and many kinds of devices don't reach the market because they have to compete with traditional devices like glass-based OLEDs, Si-based rigid photovoltaics and many other types of devices, and the added production costs are too high even when

the higher functionality is considered. Thus, lowering the manufacturing costs of flexible devices can lead to more feasible commercialization.

ERGIS noDIFFUSION® FILMS ARE

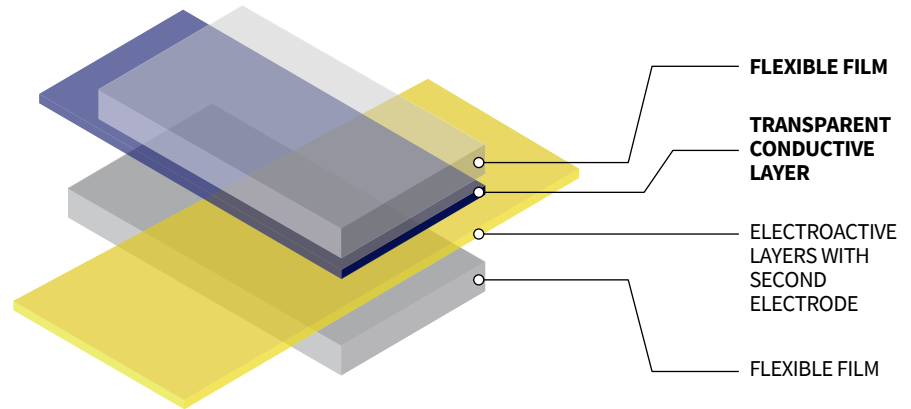


ERGIS noDIFFUSION[®] BARRIER FILMS



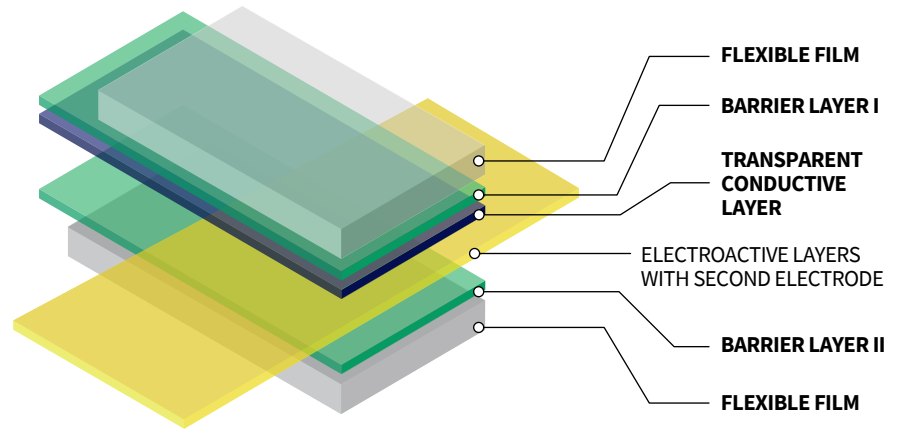
Substrate	PET, PMMA
Water Vapor Transmission Rate (WVTR)	10^{-6} g/m ² 24h
Oxygen Transmission Rate (OTR)	10^{-4} cm ³ /m ² 24h
Film Thickness	12-150 μ m
Transmittance	> 90% in the visible range
Other properties	Weather resistant, UV stable

ERGIS noDIFFUSION[®] FILMS WITH A TRANSPARENT CONDUCTIVE LAYER



Substrate	PET, PMMA
Surface conductivity	15 ohm/square
Film Thickness	12-150 µm
Transmittance	> 80% in the visible range
Other properties	Weather resistant, UV stable

ERGIS noDIFFUSION[®] BARRIER FILMS WITH A TRANSPARENT CONDUCTIVE LAYER



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Ergis noDiffusion®

film technology is being developed by the **ERGIS GROUP** in co-operation with its partners.



The **ERGIS GROUP**, which has been developed consistently since 1998, is a leader in plastics processing in Central and Eastern Europe. The Group consists of modern and innovative companies, which makes it an example of a dynamic enterprise with a stable market position. Our organisational culture is based on: expansion, sustainable development and innovativeness.



CIRCULAR PACKAGING DESIGN was established in January 2018 as part of Ergis Group when the EU announced its new Strategy for Plastic. Its main objective is design and production implementation of packaging complying with Circular Economy requirements.

Ergis ultra barrier film noDiffusion[®]

www.ergisnodiffusion.com

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